

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	692	(438/110).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/02 11:27
L2	299	(427/98.4).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/02 11:27
L3	243	(427/96.1).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/02 11:27
L4	1611	(438/113).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/02 11:27
L5	824	(ball\$1 near3 (terminal \$1 solder grid)) and (l1 l2 l3 l4)	US-PGPUB; USPAT	OR	OFF	2009/08/02 11:27
L6	113	(ball\$1 near3 (terminal \$1 solder grid)) and (l1 l2 l3 l4) and (protect\$3 adj layer)	US-PGPUB; USPAT	OR	OFF	2009/08/02 11:28
L7	41	l5 and (stress ((force pressure) near3 appl \$10)) with (separat\$3 dicing breaking fracture \$1)	US-PGPUB; USPAT	OR	OFF	2009/08/02 11:28
L8	277	(427/96.2).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/02 11:31
L9	46	(427/96.5).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/02 11:32

L12	5	(groove\$1 and buffer and circuit and convex and concave).clm.	US-PGPUB; USPAT	OR	OFF	2009/08/02 11:39
S1	5	(suzuki near2 ryuusuke).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/13 17:11
S2	222	(427/96.1).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/13 17:13
S3	26	(ball\$1 and (slot\$1 channel\$1 groove\$1) and (electronic\$1 circuit \$1) and (force or stress) near2 (applied application))	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/13 17:16
S4	98	(ball\$1 and (slot\$1 channel\$1 groove\$1) and (electronic\$1 circuit \$1) and (force or stress) near2 (applied application)).clm.	US-PGPUB; USPAT	OR	OFF	2009/01/13 17:17
S5	722	((ball\$1 or projections) near3 (array or plurality) and (slot\$1 channel\$1 groove\$1) and (electronic\$1 circuit \$1) and (packag\$3 or mount\$3)).clm.	US-PGPUB; USPAT	OR	OFF	2009/01/13 17:22
S6	308	((ball\$1 or projections) near3 (array or plurality) and (slot\$1 channel\$1 groove\$1) and (electronic\$1 circuit \$1) and (packag\$3 or mount\$3))	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/13 17:22
S7	37	((ball\$1 or projections) near3 (array or plurality) and (slot\$1 channel\$1 groove\$1) and (electronic\$1 circuit \$1) and (packag\$3 or mount\$3) and (separat \$3 or divid\$3 or dicing))	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/13 17:23

S8	35	((ball\$1 adj (grid or array)) and (slot\$1 channel\$1 groove\$1) and (electronic\$1 circuit \$1) and (packag\$3 or mount\$3) and (separat \$3 or divid\$3 or dicing))	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/13 17:27
S9	188	((ball\$1 adj (grid or array)) and (slot\$1 channel\$1 groove\$1) and (electronic\$1 circuit \$1) and (packag\$3 or mount\$3)).clm.	US-PGPUB; USPAT	OR	OFF	2009/01/13 17:30
S10	4	"2003017829"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/30 13:34
S11	6	(ball\$1 near3 terminal \$1) and (slot\$1 channel \$1 groove\$1) and (electronic\$1 circuit\$1) and separat\$4	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/30 13:35
S12	44	(ball\$1 near3 terminal \$1) and (slot\$1 channel \$1 groove\$1) and (electronic\$1 circuit\$1)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/30 13:35
S13	75	(ball\$1 near3 terminal \$1) and (slot\$1 channel \$1 groove\$1 separat\$3 dicing) and (electronic \$1 circuit\$1)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/30 13:36
S14	38	(ball\$1 near3 terminal \$1) and (separat\$3 dicing) and (electronic \$1 circuit\$1)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/30 13:39
S15	48	(ball\$1 near3 solder) and (dicing) and (electronic\$1 circuit\$1)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/30 13:41
S16	2	("6326677").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/27 11:42
S17	63	(ball\$1 near3 (terminal \$1 solder grid)) and (slot\$1 channel\$1 groove\$1) and (separat \$3 dicing) and (electronic\$1 circuit\$1)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/27 11:43

S18	111	((ball\$1 near3 (terminal \$1 solder grid)) and (slot\$1 channel\$1 groove\$1) and (separat\$3 dicing))	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/27 11:44
S19	237	((ball\$1 near3 (terminal \$1 solder grid)) and (slot\$1 channel\$1 groove\$1) and (separat\$3 dicing)).clm.	US-PGPUB; USPAT	OR	OFF	2009/02/27 11:50
S20	239	((ball\$1 near3 (terminal \$1 solder grid)) and (slot\$1 slotted channel \$1 groove\$1) and (separat\$3 dicing)).clm.	US-PGPUB; USPAT	OR	OFF	2009/02/27 11:51
S21	2	S20 not S19	US-PGPUB; USPAT	OR	OFF	2009/02/27 11:51
S22	271	((ball\$1 near3 (terminal \$1 solder grid)) and ((\$2scribe\$1 near2 line \$1) slot\$1 channel\$1 groove\$1) and (separat\$3 dicing break\$3)).clm.	US-PGPUB; USPAT	OR	OFF	2009/02/27 11:55
S23	34	S22 not S19	US-PGPUB; USPAT	OR	OFF	2009/02/27 11:56
S24	1506	(438/113).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/27 12:00
S25	227	(427/96.1).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/27 12:00
S26	23	(ball\$1 near3 (terminal \$1 solder grid)) and S25	US-PGPUB; USPAT	OR	OFF	2009/02/27 12:00
S27	281	(427/98.4).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/27 12:05
S28	2	("6054338").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/01 15:09

S29	31	(ball\$1 near3 (terminal \$1 solder grid)) and (silver with resin)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/01 23:05
S30	11492	(ball\$1 near3 (terminal \$1 solder grid)) and (silver conduct\$4 bond \$3 resin)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/01 23:07
S31	124	(ball\$1 near3 (terminal \$1 solder grid)) and (silver and conduct\$4 and bond\$3)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/01 23:07
S32	78	(ball\$1 near3 (terminal \$1 solder grid)) and (silver and conduct\$4 and bond\$3 and (resin polymer epoxy))	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/01 23:08
S33	21	(ball\$1 and (slot\$1 channel\$1 groove\$1) and (electronic\$1 circuit \$1) and (breaking)). clm.	US-PGPUB; USPAT	OR	OFF	2009/03/01 23:12
S34	3	"07022213"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/01 23:16
S35	3	"05029102"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/01 23:18
S36	0	(ball\$1 near3 (terminal \$1 solder grid)) and (terminal41 with conduct\$4 near4 bond \$3)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/02 10:12
S37	512	(ball\$1 near3 (terminal \$1 solder grid)) and (conduct\$4 near4 bond \$3)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/02 10:12
S38	270	(ball\$1 near3 (terminal \$1 solder grid)) and (conduct\$4 near4 bonding)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/02 10:12
S39	49	(ball\$1 near3 (terminal \$1 solder grid)) and (conduct\$4 near3 (ink adhesive polymer resin) near4 bond\$3)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/02 10:13

S40	3	JP2001053033A	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/02 10:32
S41	881	((evaporation vaporization vaporizing) near2 apparatus).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/02 15:32
S42	1653	((evaporation vaporization vaporizing) near2 apparatus).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/02 15:33
S43	517	((evaporation vaporization vaporizing) near2 apparatus).ti.	US-PGPUB; USPAT	OR	OFF	2009/03/02 15:34
S44	36	(ball\$1 near3 (terminal \$1 solder grid)) and (buffer near2 stress\$3)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/01 12:46
S45	5	(suzuki near2 ryuusuke).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/01 12:48
S46	243	(ball\$1 near3 (terminal \$1 solder grid)) and (concave)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/01 12:51
S47	215	(ball\$1 near3 (terminal \$1 solder grid)) and (protect\$3 adj layer)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/01 12:52
S48	9	(ball\$1 near3 (terminal \$1 solder grid)) and (protect\$3 adj cover)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/01 12:59
S49	13	(ball\$1 near3 (terminal \$1 solder grid)) and (covering adj (layer member))	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/01 13:00
S50	268	(ball\$1 near3 (terminal \$1 solder grid)) and (stress force pressure) and (separat\$3 dicing breaking fracture\$1)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/01 13:02

S51	147	(ball\$1 near3 (terminal \$1 solder grid)) and (stress ((force pressure) near3 appl \$10)) and (separat\$3 dicing breaking fracture \$1)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/01 13:03
S52	339	(ball\$1 near3 (terminal \$1 solder grid)).clm. and (stress ((force pressure) near3 appl \$10)) with (separat\$3 dicing breaking fracture \$1)	US-PGPUB; USPAT	OR	OFF	2009/08/01 13:10
S53	119	((ball\$1 near3 (terminal \$1 solder grid)) and (stress ((force pressure) near3 appl \$10)) and (separat\$3 dicing breaking fracture \$1)).clm.	US-PGPUB; USPAT	OR	OFF	2009/08/01 13:11
S54	245	((ball\$1 near3 (terminal \$1 solder grid)) and (protect\$3 adj (coating layer))).clm.	US-PGPUB; USPAT	OR	OFF	2009/08/01 13:24

EAST Search History (I nterference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L14	4	(groove\$1 and buffer and circuit).clm.	UPAD	OR	OFF	2009/08/02 11:49

8/ 2/ 09 12:01:31 PM

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